Silicon PNP Epitaxial

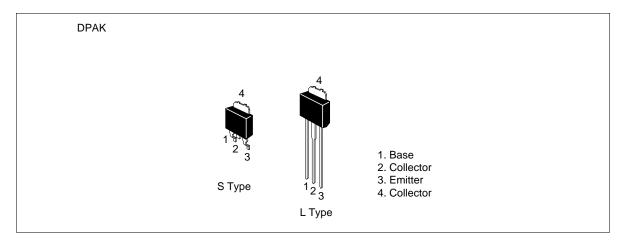
# HITACHI

ADE-208-877 (Z) 1st. Edition Sep. 2000

#### Application

Low frequency power amplifier complementary Pair with 2SD2123(L)/(S)

#### Outline





#### **Absolute Maximum Ratings** (Ta = $25^{\circ}$ C)

ltem	Symbol	Ratings	Unit
Collector to base voltage	V <sub>CBO</sub>	-180	V
Collector to emitter voltage	V <sub>CEO</sub>	-160	V
Emitter to base voltage	V <sub>EBO</sub>	-5	V
Collector current	Ι <sub>c</sub>	-1.5	А
Collector peak current	I <sub>C(peak)</sub>	-3	А
Collector power dissipation	P <sub>c</sub> * <sup>1</sup>	18	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	٥C

Note: 1. Value at  $T_c = 25^{\circ}C$ .

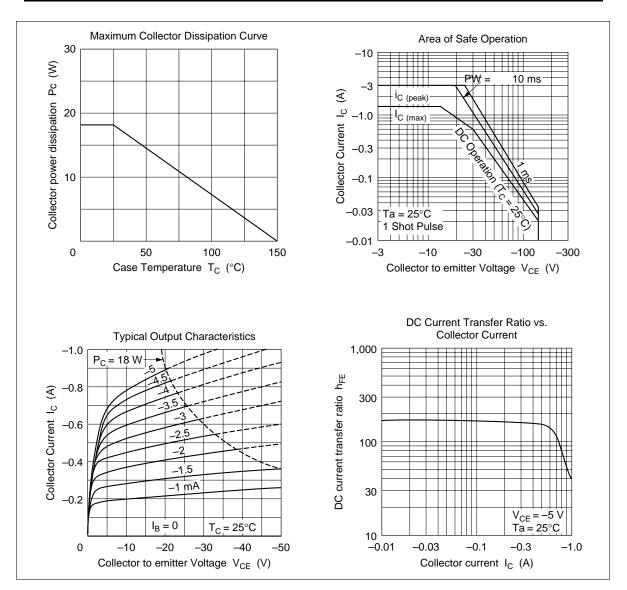
#### **Electrical Characteristics** (Ta = 25°C)

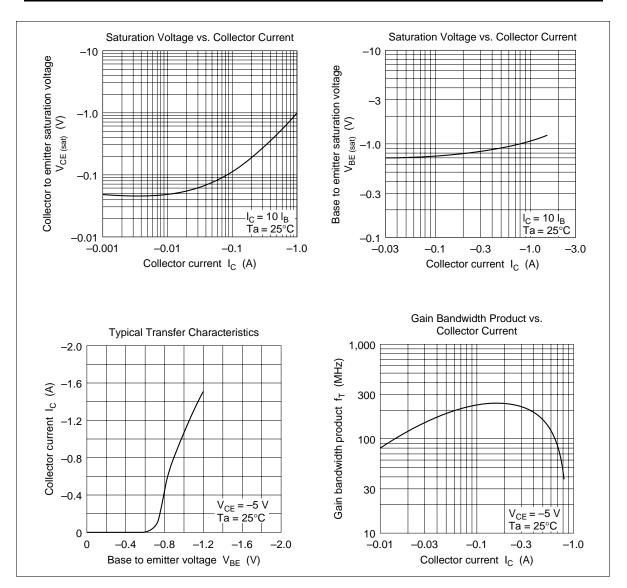
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	-180	_	_	V	$I_{c} = -1 \text{ mA}, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	-160	_	_	V	$I_c = -10 \text{ mA}, \text{ R}_{\text{BE}} = \infty$
Emitter to base breakdown voltage	$V_{\rm (BR)EBO}$	-5	—	—	V	$I_{\rm E} = -1  {\rm mA},  I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	-10	μΑ	$V_{CB} = -160 \text{ V}, I_{E} = 0$
DC current transfer ratio	$h_{\rm FE1}^{*1}$	60	_	200		$V_{ce} = -5 \text{ V}, \text{ I}_{c} = -150 \text{ mA}^{*2}$
	h <sub>FE2</sub>	30	_	_	_	$V_{ce} = -5 \text{ V}, \text{ I}_{c} = -500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-1	V	$I_{c} = -500 \text{ mA}, I_{B} = -50 \text{ mA}$
Base to emitter voltage	V <sub>BE</sub>	_	_	-1.5	V	$V_{ce} = -5 \text{ V}, \text{ I}_{c} = -150 \text{ mA}$
Gain bandwidth product	f <sub>T</sub>	_	240	_	MHz	$V_{ce} = -5 \text{ V}, \text{ I}_{c} = -150 \text{ mA}$
Collector output capacitance	Cob		25	_	pF	$V_{_{CB}} = -10 \text{ A}, I_{_{E}} = 0, f = 1 \text{ MHz}$

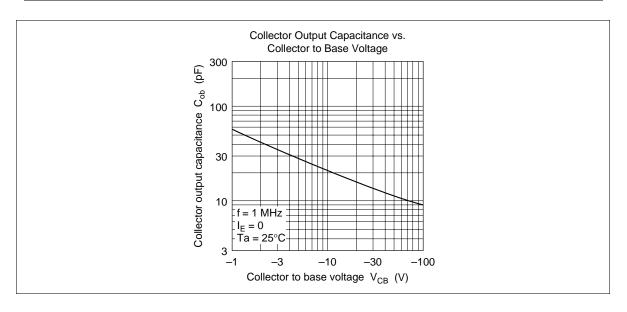
Notes: 1. The 2SB1409(L)/(S) is grouped by  $h_{\mbox{\tiny FE1}}$  as follows.

В	С
60 to 120	100 to 200

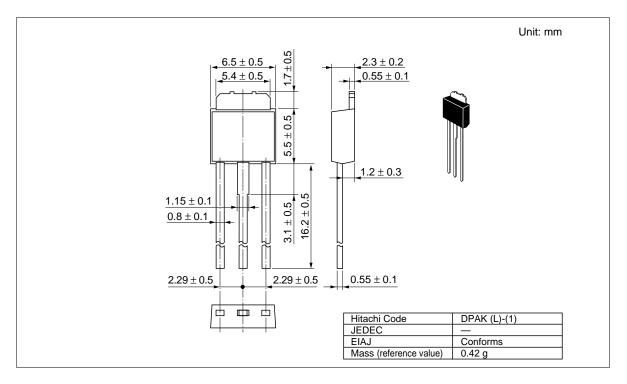
2. Pulse test.

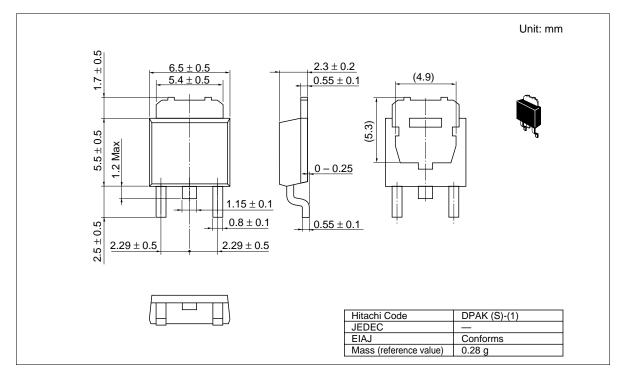






#### **Package Dimensions**





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